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## SECTION 2. FORMS PTO/SB/08A and 08B (formerly Form PTO-1449)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Felton, et al. Attorney Docket: 2550/117  
Serial No: 10/002,953 Art Group Unit: 1734  
Date Filed: October 23, 2001 Examiner Name: Not Assigned  
Invention: MEMS Capping Method and Apparatus

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS'  
INFORMATION DISCLOSURE STATEMENTUnited States Patents

Examiner Initials	Reference Number	Document Number	Issue Date	Inventor	Class/Subclass
<u>SA</u>	AA	5,915,168	Jun. 22, 1999	Salatino et al.	438/110
<u>SA</u>	AB	5,798,557	Aug. 25, 1998	Salatino et al.	257/416
<u>SA</u>	AC	5,604,160	Feb. 18, 1997	Warfield	437/209
<u>SA</u>	AD	5,594,979	Jan. 21, 1997	Borchelt et al.	29/25.35
<u>SA</u>	AE	5,323,051	Jun. 21, 1994	Adams et al.	257/417
<u>SA</u>	AF	4,786,357	Nov. 22, 1988	Campanelli et al.	156/633

Other Documents

Examiner Initials	Reference Number	Author	Title of Article, Title of Item, Date, Page(s), Volume-Issue Number(s)
<u>SA</u>	AG	Smith et al.	Micromachined Packaging for Chemical Microsensors, IEEE Trans. Electron Devices, June 1988, Vol. 35, No. 6 (pp. 787-792, numbered 192-197).
<u>SA</u>	AH	Petersen et al.	Silicon Fusion Bonding for Pressure Sensors, Rec. of the IEEE Solid-State Sensor and Actuator Workshop, 1988, pp. 144-147, numbered 209-212.
<u>SA</u>	AI	Rudolf et al.	Silicon Microaccelerometer, Transducers'87, Rec. of the 4 <sup>th</sup> Int. Conf. on Solid-State Sensors and Actuators, 1987, pp. 395-398, numbered 376-379.

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Ko et al.

Bonding Techniques for Microsensors,  
Micromachining and Micropackaging of  
Transducers, 1985, pp. 198-208.

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A Batch-Fabricated Silicon Accelerometer,  
IEEE Trans. Electron Devices, December 1979,  
Vol. ED-26, No. 12, pp. 1911-1917, numbered  
352-358.

Examiner Signature:

Richard T. Calvert

Date Considered:

10/22/03

NOTE FOR EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609;  
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